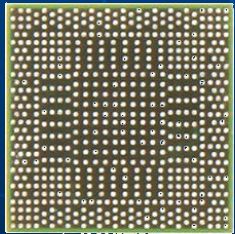
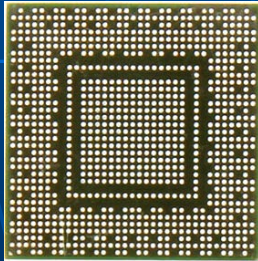
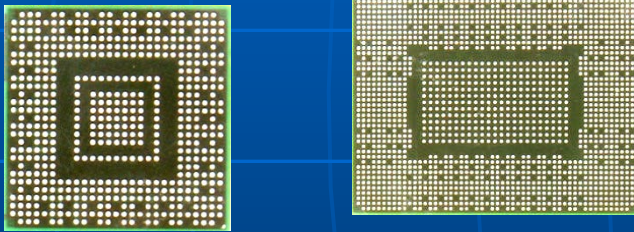
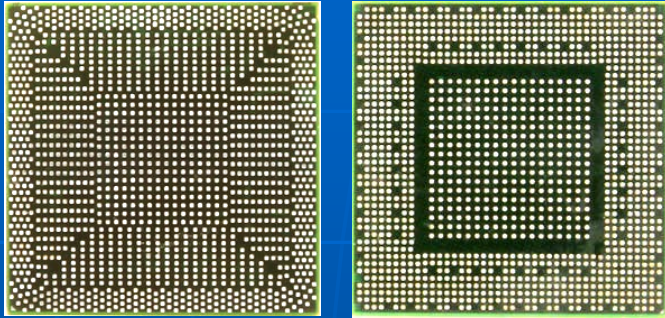


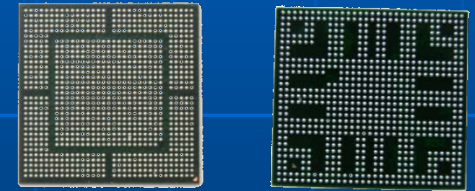
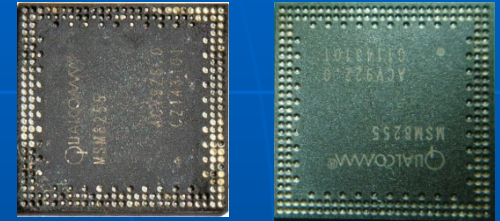


DESOLDERING AIR KNIFE TU-680W

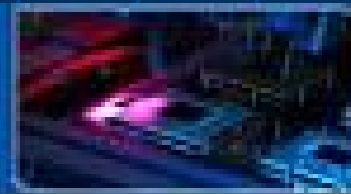
BGA-IC.



POP-IC.



solder ball void rework study



Process flow

Rework product incoming

Dipping flux

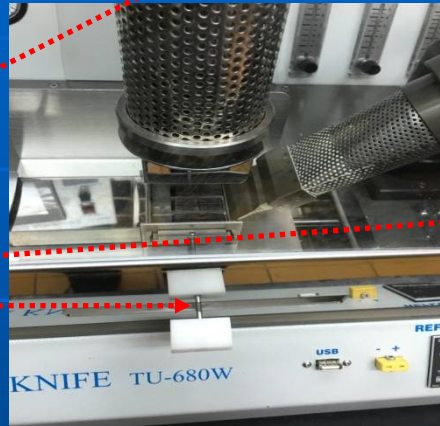
De- ball

Flux clean

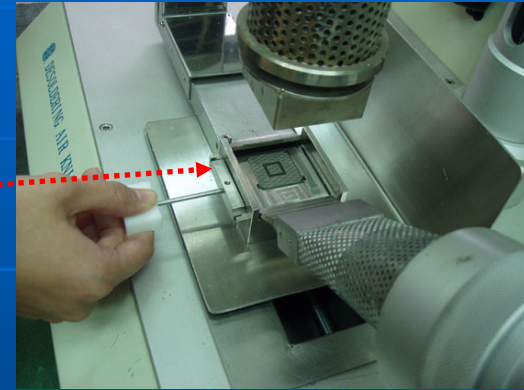
Substrate pre-bake



TU-680W-除錫機



POP



BGA

Flux clean

Reflow

Solder ball attach

BP-pretreatment

